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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application: Claims 1-5 (Canceled).

6. (Currently Amended) A solid-state imaging device having a light-receiving portion of a pixel formed in a region on the of a substrate surface, a convex lens with an upwardly curved surface which is positioned above the light-receiving portion and embedded in an inter-layer dielectric, and an on-chip lens formed above said convex lens, characterized in that said convex lens is formed on the over a depression in the surface of the underlying inter-layer dielectric such that the lower part of the lens which is made of [[the]] a light transmitting material filling said depression is integral with the upper part of the lens which is made of the same light transmitting material as that of the lower part of the lens and has the convexly curved lens surface, wherein said light transmitting material is comprised of P-SiN or P-SiO₂.